

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD50N06S2-14	**Issued**	02. June 2021
MA#	MA001910634		
Package	PG-TO252-3-11	**Weight***	372.24 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10822	10822
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		578	
	non noble metal	copper	7440-50-8	215.017	57.77	57.85	577624	578376
wire	non noble metal	aluminium	7429-90-5	3.052	0.82	0.82	8199	8199
encapsulation	inorganic material	zincoxide	1314-13-2	1.236	0.33		3320	
	miscellaneous	miscellaneous	-	6.180	1.66		16602	
	plastics	epoxy resin	-	18.540	4.98		49807	
	inorganic material	silicondioxide	60676-86-0	97.646	26.23	33.20	262318	332047
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10047	10047
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.065	0.02		174	
	noble metal	silver	7440-22-4	0.081	0.02		217	
	non noble metal	lead	7439-92-1	3.085	0.83	0.87	8287	8678
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51519	51586
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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